

Part Number: WP799EGW

High Efficiency Red
Green

Features

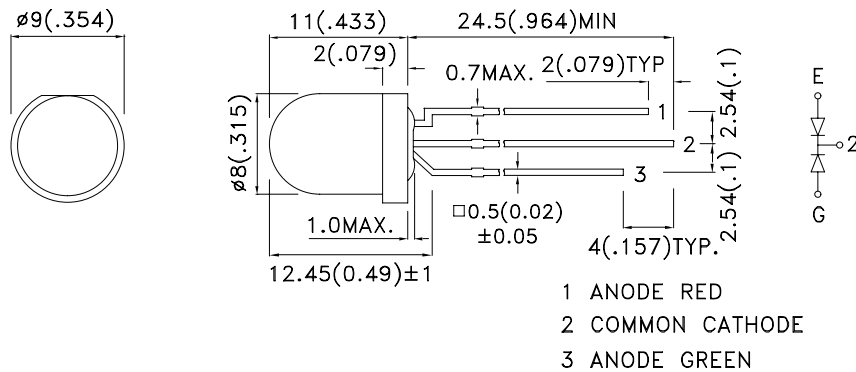
- UNIFORM LIGHT OUTPUT.
- LOW POWER CONSUMPTION.
- MILKY WHITE DIFFUSION LENS.
- 3 LEADS WITH ONE COMMON LEAD.
- I.C. COMPATIBLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. Lead spacing is measured where the lead emerge from the package.
4. Specifications are subject to change without notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP799EGW	High Efficiency Red (GaAsP/GaP)	WHITE DIFFUSED	36	80	50°
	Green (GaP)		18	50	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	High Efficiency Red Green	627 565		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	High Efficiency Red Green	625 568		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I _F =20mA
C	Capacitance	High Efficiency Red Green	15 15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red Green		10 10	uA	V _R = 5V

Notes:

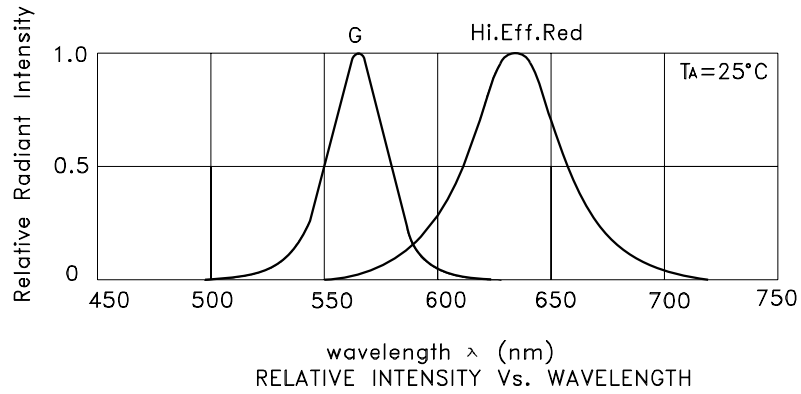
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

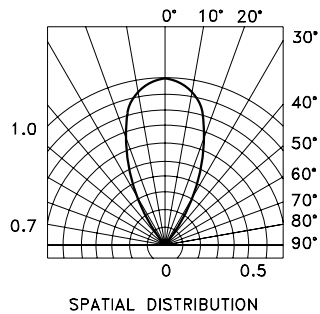
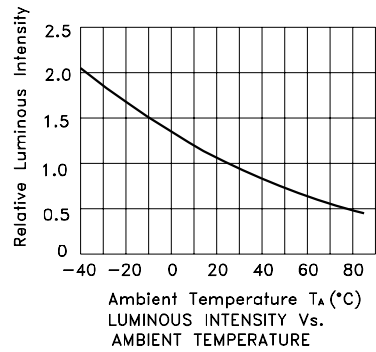
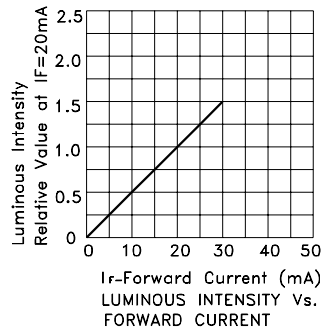
Parameter	High Efficiency Red	Green	Units
Power dissipation	75	62.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	160	140	mA
Reverse Voltage	5		V
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.

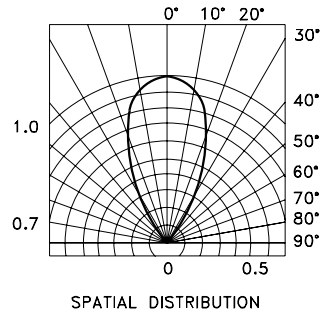
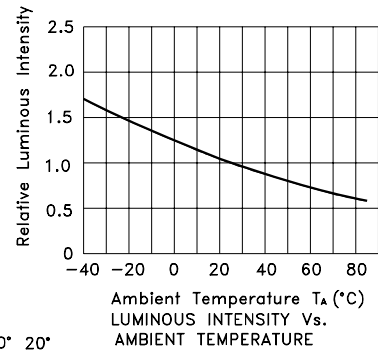
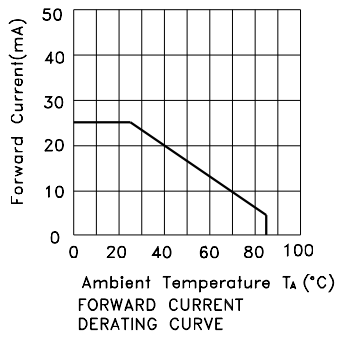
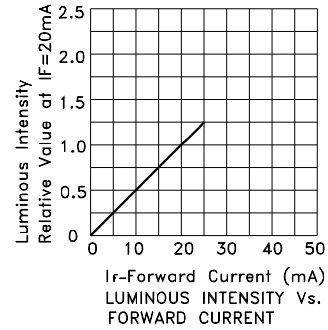
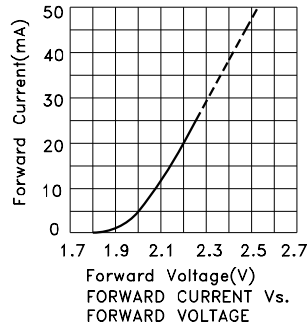


WP799EGW High Efficiency Red



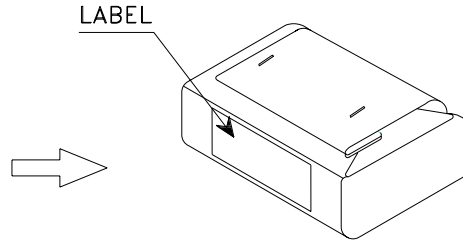
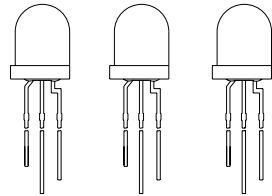
Kingbright

Green



PACKING & LABEL SPECIFICATIONS

WP799EGW

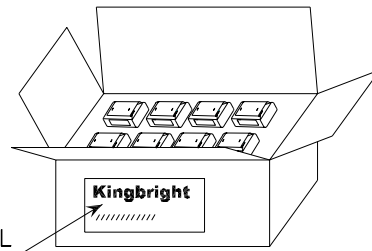
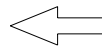


200PCS / BAG




12.8K/9# BOX

OUTSIDE LABEL



1.6K/1# BOX

OUTSIDE LABEL

<h1>Kingbright</h1>				
Q.C.	<table border="1"> <tr> <td>QC</td> </tr> <tr> <td>XX XX XX</td> </tr> <tr> <td>PASSED</td> </tr> </table>	QC	XX XX XX	PASSED
QC				
XX XX XX				
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TYPE NO : WP799xxx				
QUANTITY : 200 pcs				
S/N : XX	CODE: XX			
LOT NO : 				
RoHS Compliant				

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



Fig. 5



Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)



Fig. 7



Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.

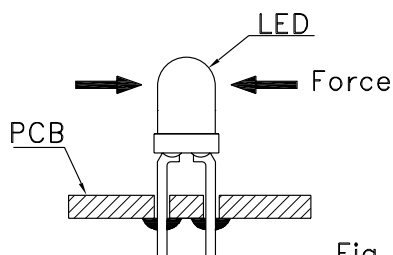


Fig. 9